

DATASHEET

3mm Advanced Super Flux LEDs

33-01-C34-YYSC-A5T1U1CH-AM

Feature

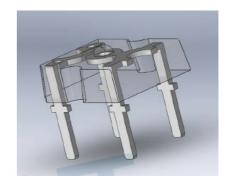
- · Lead-Free
- · RoHS compliant.
- · Low profile.
- · Uniform color
- · High flux output
- · Colorless clear resin.
- 7150 to 14250 mlm at 70mA.
- · Qualification according to AEC-Q101.
- · Packaged in tubes for use with automatic insertion equipment.
- · Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Applications

- Automotive exterior lighting: Turn light, tail light, rear-view mirror light, side light, license light switch, 3rd braking light...etc.
- Substitution of traditional light.
- · Electronic Signs and Signals.
- General applications.

Device Selection Guide

Chip	Emitted Color	Dogin Color	
Material	Ellitted Color	Resin Color	
AlGaInP	Yellow	Water Clear	



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Product Nomenclature

3 3	 01	C3	4	1.1-	YYS	С	A5	T1U1	С	Н	AM
1	2	3	4		5	6	7	8	9	10	11

The product name is designated as below:

1.	Product type
2.	Lead-frame type
3.	Angle
4.	Product pasted without Zener
5.	Chip code
6.	Resin color
7.	Wavelength
8.	Power &Luminous Intensity
9.	Range of Forward Voltage specification
10.	Operation current
11	Application



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V _R	5	V	
Continuous Forward Current	lF	70	mA	
Power Dissipation	P _d	220	mW	
LED Junction Temperature	Tj	115	$^{\circ}$ C	
Operating Temperature	Торг	-40 ~ +100	$^{\circ}$ C	
Storage Temperature	$T_{\rm stg}$	-40 ~ +110	°C	
Thermal Resistance	Rth _{J-A}	140	K/W	
ESD (Classification acc. AEC Q101)	ESD _{HBM}	2000 200	V	
Soldering Temperature(T=5 sec)	col	Wave Soldering : 260 °C for 5 sec. Hand Soldering : 350 °C for 3 sec.		



Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Total Flux	Ф٧	7150		14250	mlm	I _F =70mA
Peak Wavelength	λ_{p}		592		nm	I _F =70mA
Dominant Wavelength	λ_{d}	590		598	nm	I _F =70mA
Spectrum Radiation Bandwidth	Δλ		15		nm	I _F =70mA
Viewing Angle	2θ _{1/2}		105		deg	I _F =70mA
Forward Voltage	VF	1.9		2.9	V	I _F =70mA
Reverse Current	I _R			10	μΑ	V _R =5V
Note:						

Note:

1. Tolerance of Total Flux: ±11%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Forward Voltage

Bin	Min.	Max.	Unit	Condition
2	1.9	2.1		
3	2.1	2.3		
4	2.3	2.5	V	I _F =70mA
5	2.5	2.7		
6	2.7	2.9		

Tolerance of Forward Voltage: ±0.1V



Bin Range of Dominant Wavelength

Bin	Min.	Max.	Unit	Condition
4	590	592		
5	592	594		
6	594	596	nm	I _F =70 mA
7	596	598		

Note:

Tolerance of Dominant Wavelength: ±1nm

Bin Range of Total Flux

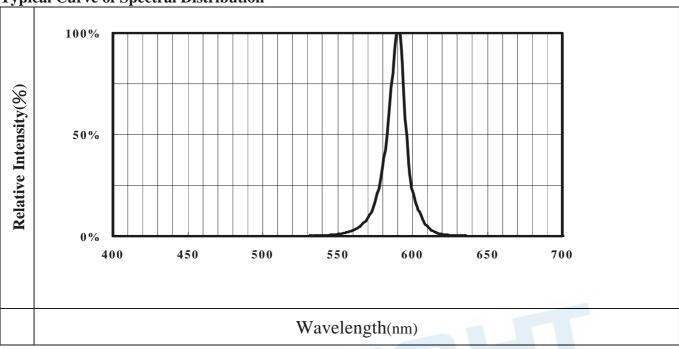
Bin	Min.	Max.	Unit	Condition
T1	7150	9000		
T2	9000	11250	mlm	I _F =70mA
U1	11250	14250		

Note:

Tolerance of Total Flux: ±11%

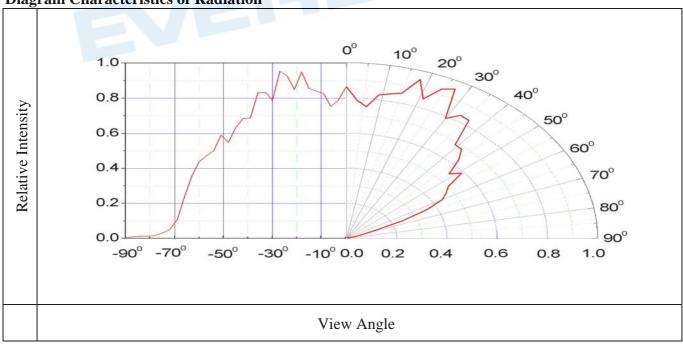
Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution



Note: $V(\lambda)$ =Standard eye response curve; I_F =20mA

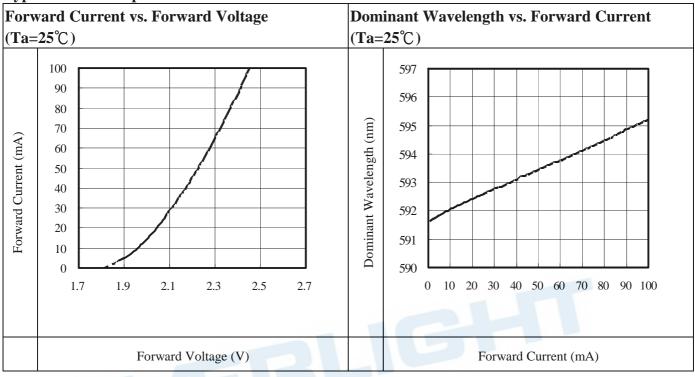
Diagram Characteristics of Radiation

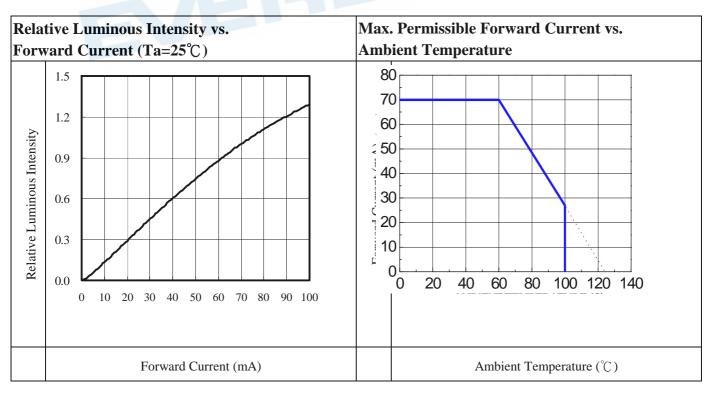


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Typical Electro-Optical Characteristics Curves

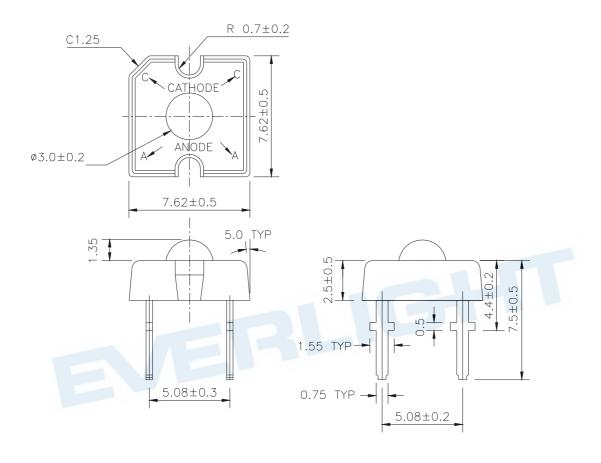
Typical Curve of Spectral Distribution







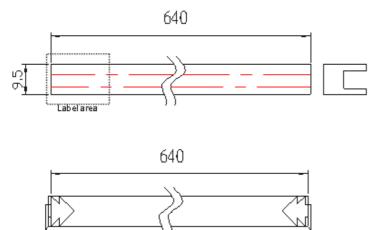
Package Dimension

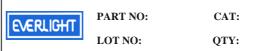


Note: Tolerances unless mentioned ± 0.25 mm. Unit = mm



Antistatic Packing Materials Tube Tube



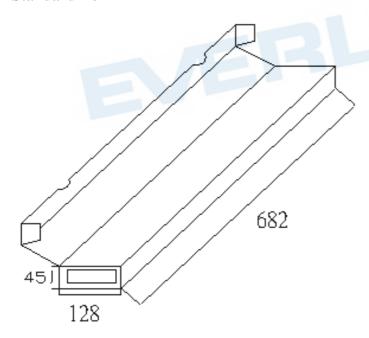


Tube Label Explanation

- QTY: Packing Quantity
- LOT No: Lot Number
- CAT: Rank of (VF)(Note*)(ΦV)
 Note: λ_d/CIE/Color temperature

Note: Tolerances unless mentioned ± 2.0 mm. Unit = mm

Standard Box





Outer Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- CAT: Rank of (Note*)
 - Note: λ_d /CIE/Color temperature
- Luminous Flux(Intensity)
- HUE/REF: Reference
- · LOT No: Lot Number

Note: Tolerances unless mentioned ± 3.0 mm. Unit = mm

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Packing Quantity

Packing material	$Length \times Width \times height (mm)$	Tube Quantity (Pcs)	LED Quantity (Pcs)
Tube	640 x 9.5 x12	1	80
Standard box	682 x 128 x 45	36	2880
Large box	702 x 420 x 164	324	25920

Note:

- 1. Normal packing specification is use standard box, unless already defined initially.
- 2. Vacuum packing with anti-static bag after packing in standard box.
- 3. Specifications are subject to change without prior notice.

Notes

1. Lead Forming

- During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- Lead forming should be done before soldering.
- Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

2. Storage

- The LEDs should be stored at 30°C or less and 60%RH or less after being shipped from Everlight and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

3. Soldering

- Careful attention should be paid during soldering. Solder the LED no lower than 1.6mm from the base of stopper is recommended.
- Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.

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■ Recommended soldering conditions:

Hand	Soldering	DII	P Soldering
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)
Soldering time	3 sec Max.	Bath temp.	260 Max.
Distance	No lower than 1.6mm from	Bath time.	5 sec Max.
	the base of stopper		
		Distance	No lower than 1.6mm from
			the base of stopper

- Dip and hand soldering should not be done more than one time.
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- Although the recommended soldering conditions are specified in the above table, dip or handsoldering at the lowest possible temperature is desirable for the LEDs.
- Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.

4. Cleaning

- When necessary, cleaning should occur only with isopropyl alcohol at room temperature for a duration of no more than one minute. Dry at room temperature before use.
- Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Ultrasonic cleaning shall be pre-qualified to ensure this will not cause damage to the LED

5. Heat Management

- Heat management of LEDs must be taken into consideration during the design stage of LED application. The current should be de-rated appropriately by referring to the de-rating curve found in each product specification.
- The temperature surrounding the LED in the application should be controlled. Please refer to the data sheet de-rating curve.

6. ESD (Electrostatic Discharge)

- Electrostatic discharge (ESD) or surge current (EOS) can damage LEDs.
- An ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling LEDs.
- All devices, equipment and machinery must be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing.

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7. Other

- Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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- This product is not intended to be used for military, aircraft, medical, life sustaining or life saving 6. applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.

Revision History

Rev.	Modified date		File modified contents	
2	2013/5/24		Change the form of datasheet	
3	2014/7/11		Change the packing specification	
4	2023/9/8		SIX additional statements	